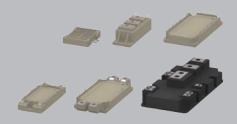


- Contributes to energy savings by reducing power loss Reduces inverter loss by 10% and lower chip temperature by 11°C (Comparison with the 6th Generation V Series (1200V 75A), at  $f_{\rm c}$  = 8 kHz)
- Achieves equipment miniaturization
   Footprint size can be reduced by 36% by replacing the previous
   6th Generation (1200V 75A) with the new 7th Generation X Series
   (1200V 75A) (\*1)
- Contributes to improved equipment reliability Achieves guaranteed continuous operation at  $T_{\rm vjop}$  = 175°C
- · Increased rated current with RC-IGBT technology.

\*1 Mounting area ratio with 1200V PIM models



Packages (typical examples)

Application example: General motor drives UPS, PCS, others





### 1. Low loss

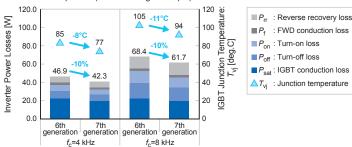
The surface and vertical structures of the IGBT and diode chips are optimized.

This reduces power losses during inverter operation compared with previous products (6th generation V series).



Reduces inverter loss by 10% and chip temperature by 11°C (Comparison with the 6th Generation V Series (1200V 75A), at  $f_c = 8 \text{ kHz}$ 

#### Inverter loss comparison (standard usage example)

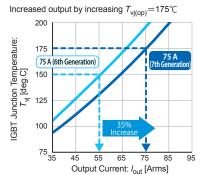


## High-temperature operation

Achieves continuous operation at 175°C through chip optimization, improved package reliability and heat resistance.



the previous generation  $\Delta T_{vi}$  power cycle lifetime is doubled compared to the conventional products, thus the same level of lifetime is secured even at 175°C continuous operation.

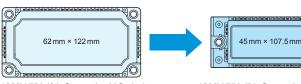


### 2. Miniaturization

The newly developed insulating substrate is applied to improve the heat dissipation of the module. By suppressing heat generation as well as reducing power loss, some products can be mounted in a package of about 36% smaller.

Application example)

## 36% reduction

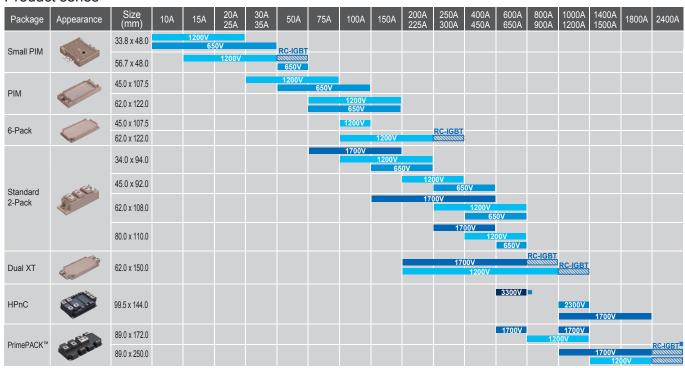


1200V 75A (6th Generation V Series)

1200V 75A (7th Generation X Series)

6

### **Product series**



\*Under development

Power Integrated Modules are products that integrate multiple circuits in one module. PrimePACK™ are registered trademarks of Infineon Technologies AG

# Safety Precautions

\*Before using this product, read the "Instruction Manual" and "Specifications" carefully, and consult with the retailer from which you purchased this product as necessary to use this product correctly. \*The product must be handled by a technician with the appropriate skills.

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